

Publication

EP 0786535 A4 19970730

Application

EP 95908373 A 19950214

Priority

- JP 9500200 W 19950214
- JP 4185094 A 19940216

Abstract (en)

[origin: WO9522634A1] An aluminum alloy ingot containing not less than 0.4 % by weight and less than 1.7 % by weight of Si, not less than 0.2 % by weight and less than 1.2 % by weight of Mg, and Al and unavoidable impurities for the remainder is homogenized at a temperature of not lower than 500 DEG C; the resultant product being cooled from a temperature of not lower than 500 DEG C to a temperature in the range of 350-450 DEG C and started to be hot rolled; the hot rolling step being finished at a temperature in the range of 200-300 DEG C; the resultant product being subjected to cold rolling at a reduction ratio of not less than 50 % immediately before it has been solution-treated; the cold rolled product being then solution-treated in which it is retained at a temperature in the range of 500-580 DEG C at a temperature increasing rate of not less than 2 DEG C/s for not more than 10 minutes; the resultant product being subjected to hardening in which it is cooled to a temperature of not higher than 100 DEG C at a cooling rate of not less than 5 DEG C/s. Thus, a method of manufacturing an aluminum alloy plate for molding is provided which has high strength and moldability and an excellent external appearance of a post-molding surface thereof, and which is suitably used as a material for transportation equipment parts, such as an outer plate for automobiles.

IPC 1-7

C22F 1/05

IPC 8 full level

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CPC (source: EP)

C22C 21/02 (2013.01); **C22C 21/08** (2013.01); **C22F 1/043** (2013.01); **C22F 1/05** (2013.01)

Citation (search report)

- [A] EP 0531118 A1 19930310 - SKY ALUMINIUM [JP]
- [A] EP 0480402 A1 19920415 - SUMITOMO LIGHT METAL IND [JP]
- [A] DE 3829911 A1 19890316 - KOBE STEEL LTD [JP], et al
- See references of WO 9522634A1

Cited by

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